



YAMAP0347USB

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AMENDMENT

Please cancel non-elected claims 1-7 and 16-20, without prejudice.

Please amend claims 8, 11, 12 and 15 so as to read as follows:

*B1 S1*  
8. (Amended) A lamination ceramic chip inductor, comprising at least one conductive pattern, the at least one conductive pattern having a thickness of  $10 \mu\text{m}$  or more and a width to thickness ratio from 1 to less than 5.

*B2 S2*  
11. (Amended) A lamination ceramic chip inductor, according to claim 8, further comprising at least one pair of insulation layers having the at least one conductive pattern formed therebetween,

wherein the at least one pair of insulation layers are magnetic.

*S2*  
12. (Amended) A lamination ceramic chip inductor, comprising at least one conductive pattern formed by an electroforming process using a photoresist, the at least one conductive pattern having a thickness of  $10 \mu\text{m}$  or more and a width to thickness ratio from 1 to less than 5.

*B3*  
15. (Amended) A lamination ceramic chip inductor, according to claim 12, further comprising at least one pair of insulation layers having the at least one conductive pattern formed therebetween,

wherein the at least one pair of insulation layers are magnetic.

A version of the above amended claims marked to indicate the specific amendments may be found in the attached Appendix, in accordance with 37 CFR 1.121(c)(1).

Please add the following new claims 21-28:

*525  
D3*

21. (New) A lamination ceramic chip inductor, comprising at least one conductive pattern formed between at least one pair of insulation layers so as to have no specific gap between the at least one conductive pattern and the at least one pair of insulation layers, the at least one conductive pattern having a thickness of  $10 \mu\text{m}$  or more and a width to thickness ratio from 1 to less than 5.

*525*

22. (New) A lamination ceramic chip inductor, according to claim 21, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

*525*

23. (New) A lamination ceramic chip inductor, according to claim 22, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

*525*

24. (New) A lamination ceramic chip inductor, according to claim 21, wherein the at least one pair of insulation layers are magnetic.

*525*

25. (New) A lamination ceramic chip inductor, comprising at least one conductive pattern formed by an electroforming process using a photoresist, the at least one conductive pattern having a thickness of  $10 \mu\text{m}$  or more and a width to thickness ratio from 1 to less than 5,

wherein the at least one conductive pattern is formed between at least one pair of insulation layers so as to have no specific gap therebetween.

26. (New) A lamination ceramic chip inductor, according to claim 25, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.